

**TRADEMARK ASSIGNMENT**

Electronic Version v1.1  
 Stylesheet Version v1.1

<b>SUBMISSION TYPE:</b>		NEW ASSIGNMENT	
<b>NATURE OF CONVEYANCE:</b>		SECURITY INTEREST	
<b>CONVEYING PARTY DATA</b>			
<b>Name</b>	<b>Formerly</b>	<b>Execution Date</b>	<b>Entity Type</b>
ENDWAVE CORPORATION		12/09/2011	CORPORATION: DELAWARE
<b>RECEIVING PARTY DATA</b>			
<b>Name:</b>	SILICON VALLEY BANK		
<b>Street Address:</b>	3003 Tasman Drive		
<b>City:</b>	Santa Clara		
<b>State/Country:</b>	CALIFORNIA		
<b>Postal Code:</b>	95054		
<b>Entity Type:</b>	CORPORATION: CALIFORNIA		
<b>PROPERTY NUMBERS Total: 1</b>			
<b>Property Type</b>	<b>Number</b>	<b>Word Mark</b>	
<b>Registration Number:</b>	2496013	ENDWAVE	
<b>CORRESPONDENCE DATA</b>			
<b>Fax Number:</b>	(408)852-4475		
<b>Phone:</b>	4088417195		
<b>Email:</b>	dsanchezbentz@virtuallawpartners.com		
<i>Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent via US Mail.</i>			
<b>Correspondent Name:</b>	Diana Sanchez Bentz, Legal Specialist		
<b>Address Line 1:</b>	VLP Law Group LLP		
<b>Address Line 2:</b>	235 Victoria Drive		
<b>Address Line 4:</b>	Gilroy, CALIFORNIA 95020		
<b>ATTORNEY DOCKET NUMBER:</b>	SVB-GIGOPTIX-ENDWAVE TM		
<b>NAME OF SUBMITTER:</b>	Diana Sanchez Bentz		
<b>Signature:</b>	/dsb1068/		

OP \$40.00 2496013

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**TRADEMARK**  
**REEL: 004676 FRAME: 0654**

Date:

12/12/2011

**Total Attachments: 11**

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## INTELLECTUAL PROPERTY SECURITY AGREEMENT

This Intellectual Property Security Agreement (this "Agreement") is entered into as of December 9, 2011 by and between SILICON VALLEY BANK ("Bank") and ENDWAVE CORPORATION ("Grantor").

### RECITALS

A. Bank has agreed to make certain advances of money and to extend certain financial accommodation to Grantor (the "Loans") in the amounts and manner set forth in that certain Amended and Restated Loan and Security Agreement by and among Bank, Grantor, GigOptix, Inc. and ChipX, Inc. dated the Effective Date (as the same may be amended, modified or supplemented from time to time, the "Loan Agreement"; capitalized terms used herein are used as defined in the Loan Agreement). Bank is willing to make the Loans to Grantor, but only upon the condition, among others, that Grantor shall grant to Bank a security interest in certain Copyrights, Trademarks, Patents, and Mask Works (as each term is described below) to secure the obligations of Grantor under the Loan Agreement.

B. Pursuant to the terms of the Loan Agreement, Grantor has granted to Bank a security interest in all of Grantor's right, title and interest, whether presently existing or hereafter acquired, in, to and under all of the Collateral.

NOW, THEREFORE, for good and valuable consideration, receipt of which is hereby acknowledged, and intending to be legally bound, as collateral security for the prompt and complete payment when due of its obligations under the Loan Agreement, Grantor hereby represents, warrants, covenants and agrees as follows:

### AGREEMENT

To secure its obligations under the Loan Agreement, Grantor grants and pledges to Bank a security interest in all of Grantor's right, title and interest in, to and under its intellectual property (all of which shall collectively be called the "Intellectual Property Collateral"), including, without limitation, the following:

(a) Any and all copyright rights, copyright applications, copyright registrations and like protections in each work or authorship and derivative work thereof, whether published or unpublished and whether or not the same also constitutes a trade secret, now or hereafter existing, created, acquired or held, including without limitation those set forth on Exhibit A attached hereto (collectively, the "Copyrights");

(b) Any and all trade secrets, and any and all intellectual property rights in computer software and computer software products now or hereafter existing, created, acquired or held;

(c) Any and all design rights that may be available to Grantor now or hereafter existing, created, acquired or held;

(d) All patents, patent applications and like protections including, without limitation, improvements, divisions, continuations, renewals, reissues, extensions and

continuations-in-part of the same, including without limitation the patents and patent applications set forth on Exhibit B attached hereto (collectively, the “Patents”);

(e) Any trademark and servicemark rights, whether registered or not, applications to register and registrations of the same and like protections, and the entire goodwill of the business of Grantor connected with and symbolized by such trademarks, including without limitation those set forth on Exhibit C attached hereto (collectively, the “Trademarks”);

(f) All mask works or similar rights available for the protection of semiconductor chips, now owned or hereafter acquired, including, without limitation those set forth on Exhibit D attached hereto (collectively, the “Mask Works”);

(g) Any and all claims for damages by way of past, present and future infringements of any of the rights included above, with the right, but not the obligation, to sue for and collect such damages for said use or infringement of the intellectual property rights identified above;

(h) All licenses or other rights to use any of the Copyrights, Patents, Trademarks, or Mask Works and all license fees and royalties arising from such use to the extent permitted by such license or rights;

(i) All amendments, extensions, renewals and extensions of any of the Copyrights, Trademarks, Patents, or Mask Works; and

(j) All proceeds and products of the foregoing, including without limitation all payments under insurance or any indemnity or warranty payable in respect of any of the foregoing.

Grantor hereby authorizes Bank to (a) modify this Agreement unilaterally by amending the exhibits to this Agreement to include any Intellectual Property Collateral which Grantor obtains subsequent to the date of this Agreement and (b) file a duplicate original of this Agreement containing amended exhibits reflecting such new Intellectual Property Collateral.

This security interest is granted in conjunction with the security interest granted to Bank under the Loan Agreement. The rights and remedies of Bank with respect to the security interest granted hereby are in addition to those set forth in the Loan Agreement and the other Loan Documents, and those which are now or hereafter available to Bank as a matter of law or equity. Each right, power and remedy of Bank provided for herein or in the Loan Agreement or any of the Loan Documents, or now or hereafter existing at law or in equity shall be cumulative and concurrent and shall be in addition to every right, power or remedy provided for herein and the exercise by Bank of any one or more of the rights, powers or remedies provided for in this Agreement, the Loan Agreement or any of the other Loan Documents, or now or hereafter existing at law or in equity, shall not preclude the simultaneous or later exercise by any person, including Bank, of any or all other rights, powers or remedies.

[Signature page follows.]

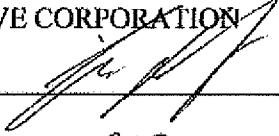
IN WITNESS WHEREOF, the parties have caused this Agreement to be duly executed by its officers thereunto duly authorized as of the first date written above.

Address of Grantor:

130 Baytech Drive  
San Jose, CA 95134  
Attn:

GRANTOR:

ENDWAVE CORPORATION

By:  \_\_\_\_\_

Title: CEO

Address of Bank:

2400 Hanover Street  
Palo Alto, CA 94304  
Attn: Megan Willard

BANK:

SILICON VALLEY BANK

By:  \_\_\_\_\_

Title: Relationship Manager

EXHIBIT A

Copyrights

Description

Registration/  
Application  
Number

Registration/  
Application  
Date

NONE

EXHIBIT B

Patents

<u>Description</u>	<u>Registration/ Application Number</u>	<u>Registration/ Application Date</u>
mmW circuit element	7,276,988	6/30/04
mmW circuit methodology	7,411,279	6/30/04
mmW circuit methodology	7,348,666	6/30/04
Comm system	7,006,794	7/25/00
Comm system	6,052,582	2/12/98
Comm system	5,771,449	8/25/95
mmW circuit methodology	7,588,966	3/4/08
mmW circuit element	7,710,219	2/28/08
mmW circuit element	7,119,633	8/24/04
High power microwave transmission element	7,145,414	6/30/04
MLMS methodology (limited)	7,109,583	5/6/04
mmW circuit element	6,600,384	5/18/01
Flip CPW methodology	6,640,423	7/18/00
Antenna	D443,873	1/20/00
High power microwave transmission element	6,518,856	10/13/99
Flip CPW Circuit	6,265,937	6/1/99
CPW circuit	6,034,580	4/23/99
Slotline Circuit	6,194,981	4/1/99
Slotline Circuit	6,094,114	8/18/98
CPW circuit	6,064,253	4/20/98
CPW circuit	6,002,305	9/25/97
Basic flip chip CPW	5,942,957	9/15/97
CPW circuit	RE35,869	7/12/97
Antenna	5,973,652	5/22/97
Flip CPW Circuit	5,821,827	12/18/96
Flip CPW Circuit	5,760,650	10/7/96
Slotline Circuit	5,983,089	10/4/96
Slotline Circuit	5,978,666	10/4/96

CPW circuit	5,821,815	9/25/96
CPW circuit	5,770,987	9/6/96
Flip CPW Circuit	5,942,804	9/3/96
Antenna	5,959,590	8/8/96
Flip CPW Circuit	5,832,376	7/12/96
CPW methodology	6,023,209	7/5/96
Basic flip chip CPW	5,668,512	6/12/96
Basic Device	5,789,801	11/9/95
Flip CPW Circuit	5,623,231	11/8/95
Flip CPW Circuit	5,610,563	11/8/95
Antenna	5,563,558	7/21/95
Basic flip chip CPW	5,528,203	6/7/95
Flip CPW Circuit	5,698,469	3/6/95
Flip CPW Circuit	5,491,449	11/19/93
mmW circuit element	Pending	2/19/09
mmW circuit element	Pending	5/23/08
mmW circuit element	Pending	5/23/08
mmW circuit methodology	Pending	5/23/08
mmW circuit methodology	Pending	5/23/08
mmW circuit methodology	Pending	3/27/07
mmW circuit methodology	Pending	6/30/04
Other	5,146,186	5/13/91
YIG methodology	4,965,967	12/22/89
YIG circuit	4,965,539	6/2/89



EXHIBIT C

Trademarks

<u>Description</u>	Registration/ Application <u>Number</u>	Registration/ Application <u>Date</u>
ENDWAVE	2496013	10/09/2001

EXHIBIT D

Mask Works

<u>Mask Number</u>	<u>Foundry</u>	<u>Description</u>
EW1XX	TriQuint	
EW113	TriQuint	High Power Ka band Switch smorg
EW114	TriQuint	VCO
EW115	TriQuint	VCO
EW116	TriQuint	0.15um Pwr PHEMT 26/38 GHz PA smorg for Phoenix
EW117	TriQuint	0.15um Pwr PHEMT 26/38 GHz PA smorg for Phoenix
EN118	TriQuint	0.15um Pwr PHEMT 38/42 GHz PAs
EN119	TriQuint	0.13um pHEMT E-Band LNAs and Mixers
EW1000	TriQuint	0.15um Pwr PHEMT 38 GHz Detector for Phoenix
<b>EW2XX</b>	<b>Northrop Grumman</b>	.....
EW201-EW213	Northrop Grumman	Engineering Mask
EW207	Northrop Grumman	Production Mask
EW211	Northrop Grumman	Production Mask
EW213	Northrop Grumman	Production Mask
EW214	Northrop Grumman	Production Mask for EWP3201ZZ
EN215	Northrop Grumman	Engineering Mask
EN216	Northrop Grumman	Engineering Mask
<b>EW3XX</b>	<b>GCS</b>	.....
EW300-xx	GCS	Attenuator engineering mask
EW300-00	GCS	Attenuator production mask, 0 dB
EW300-02	GCS	Attenuator production mask, 2 dB
EW300-03	GCS	Attenuator production mask, 3 dB
EW300-06	GCS	Attenuator production mask, 6 dB
EW300-10	GCS	Attenuator production mask, 10 dB
EW301	GCS	7 GHz PA smorg mask
EW302 thru EW305	GCS	Engineering Mask
EW306	GCS	Engineering Mask
EW306	GCS	Engineering Mask
EW307	GCS	Production mask
EW308	GCS	Production mask
EW309	GCS	Production mask
EW310	GCS	Engineering Mask
EW310	GCS	Engineering Mask
EW310	GCS	Engineering Mask
EW310	GCS	Engineering Mask
EW310	GCS	Engineering Mask
EW311	GCS	Engineering Mask
EW311	GCS	Engineering Mask
EW3000-001	GCS	Production mask
EW3000-002	GCS	Production mask
EW3000-601	GCS	Production mask
EW3010	GCS	Production mask
<b>EW3010</b>	<b>GCS</b>	<b>Production mask</b>
EW3020	GCS	Production mask
EW3020	GCS	Production mask

<b>EW3020</b>	<b>GCS</b>	<b>Production mask</b>
EW3030	GCS	Production mask
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<b>EW3030</b>	<b>GCS</b>	<b>Production mask</b>
EW3040	GCS	Production mask
<b>EW3040</b>	<b>GCS</b>	<b>Production mask</b>
EW3050	GCS	Production mask
EW3050	GCS	Production mask
<b>EW3050</b>	<b>GCS</b>	<b>Production mask</b>
EW3060	GCS	Production mask
<b>EW3060</b>	<b>GCS</b>	<b>Production mask</b>
EW3060	GCS	Engineering mask based upon BD814A and new BC layer
<b>EW4XX</b>	<b>WIN Semiconductor</b>	.....
EW400	WIN	Saphira 15 GHz smorg mask, 0.15um Power Phemt
EW401	WIN	Production mask of EW400_EB6
EW402	WIN	Phoenix smorg mask
EW402	WIN	Phoenix smorg mask with BCB
EW403	WIN	Phoenix smorg mask 2nd generation specs
EW404	WIN	Production mask of EW402_EB63 VGA EWG2303
EW405	WIN	Phoenix smorg mask 38 GHz, 26 GHz, 23 GHz
EN406	WIN	Multi-function converter chips
EN407	WIN	E-Band converter
EN408	WIN	Multi-function converter chips
EN409	WIN	Multi-function converter chips
EW4000-001	WIN	EW4001 thru EW4004 Chips
EW4000-101	WIN	EW4001 Multiplier, 32-44 GHz
EW4000-201	WIN	EW4002 VVA, 30-50 GHz
EW4000-301	WIN	EW4003 MPA, 31-41GHz
EW4000-401	WIN	EW4002 VVA, 5-20GHz
EW4010-001	WIN	EW4011 thru EW4014 Chips
EW4010-101	WIN	EW4011 Converter, 34-44 GHz
EW4010-201	WIN	EW4012 VGA, 34-40 GHz
EW4010-301	WIN	EW4013 MPA, 18-28 GHz
EW4010-401	WIN	EW4014 Multiplier, 14-26 GHz
EW4020	WIN	EW4021 thru EW4026 Chips
		TWA based on EW403_ST06, 18 and 23 GHz Mixers for HDR, 26, 38 GHz Mixer for Phoenix Loopback, 26 GHz Detector
EW4030	WIN	
EW4040	WIN	Phoenix Loopback LNA 38 GHz
		TWA based on EW403_ST06 with gate connection similar to EW402_ST03
EW4050	WIN	
EW4060	WIN	Multi-function converter chips
EW4070	WIN	EW4071 Coupler, 71 to 86 GHz
<b>Mask Number</b>	<b>Foundry</b>	<b>Description</b>
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EW3040	GCS	Production mask
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